



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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## Features

- $BV_{CEO} > 60V$
- $I_C = 3A$  Continuous Collector Current
- $I_{CM} = 8A$  Peak Pulse Current
- $R_{CE(sat)} < 90m\Omega$
- Rated to  $+175^\circ C$  – Ideal for High Ambient Temperature Environments
- Wettable Flank for Improved Optical Inspection

## Mechanical Data

- Case: PowerDI<sup>®</sup> 5060-8
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 
- Weight: 0.097 grams (Approximate)

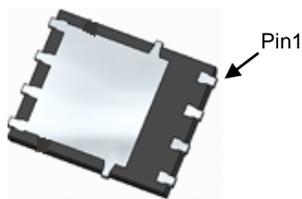
## Applications

- Power Management
- Load Switch
- Linear Mode Voltage Regulator
- Backlighting Applications

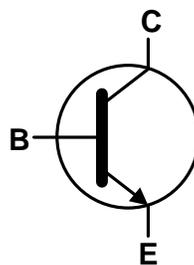
PowerDI5060-8 (SWP) (Type Q)



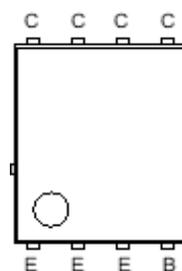
Top View



Bottom View



Internal Schematic



Top View  
Pin Configuration

**Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	60	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	V
Base Current	I <sub>B</sub>	500	mA
Continuous Collector Current	I <sub>C</sub>	3	A
Peak Pulse Collector Current	I <sub>CM</sub>	8	A

**Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

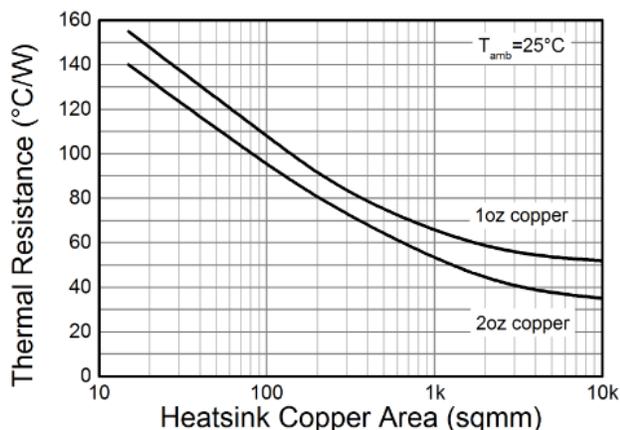
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	2.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	60	°C/W
		140 (Note 6)	
Thermal Resistance, Junction to Lead (Note 7)	R <sub>θJL</sub>	5.7	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175	°C

**ESD Ratings** (Note 8)

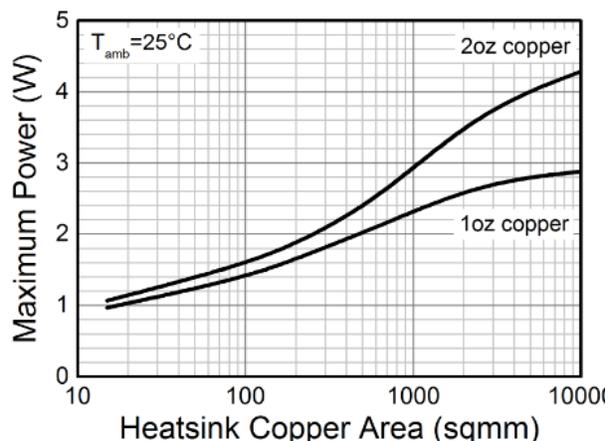
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the collector lead on 25mm x 25mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as note (5), except mounted on minimum recommended pad layout.
  7. Thermal resistance from junction to solder point (at the collector tab).
  8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

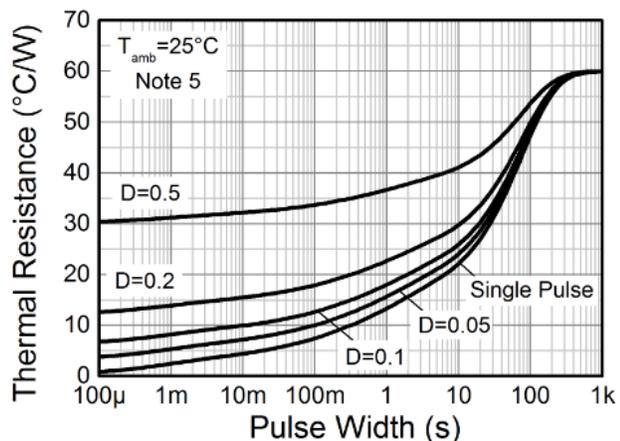
**Typical Thermal Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



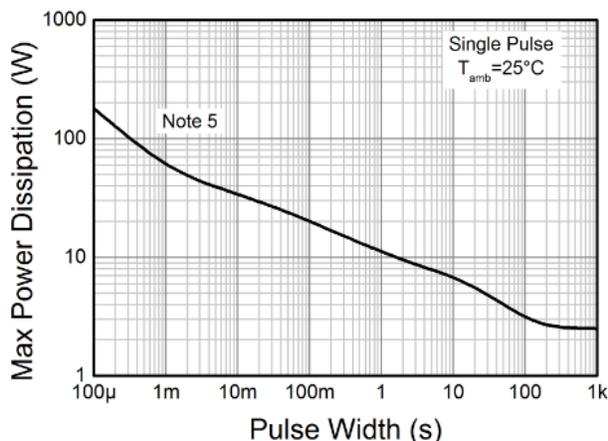
**Thermal Resistance vs. Copper Area**



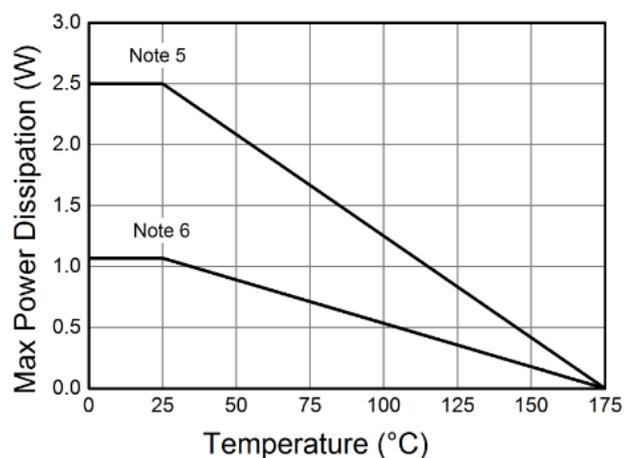
**Max Power Dissipation vs. Copper Area**



**Transient Thermal Impedance**



**Pulse Power Dissipation**



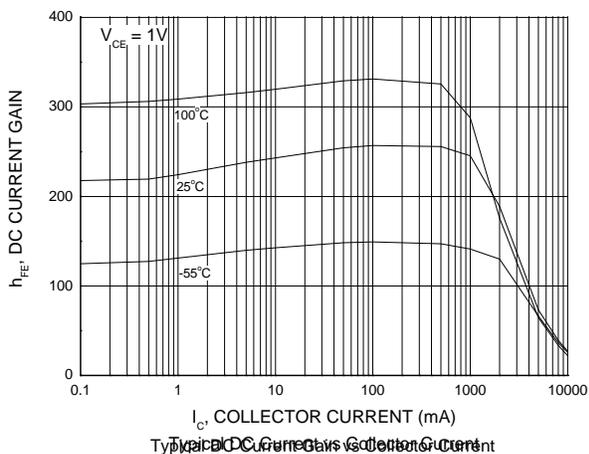
**Derating Curve**

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

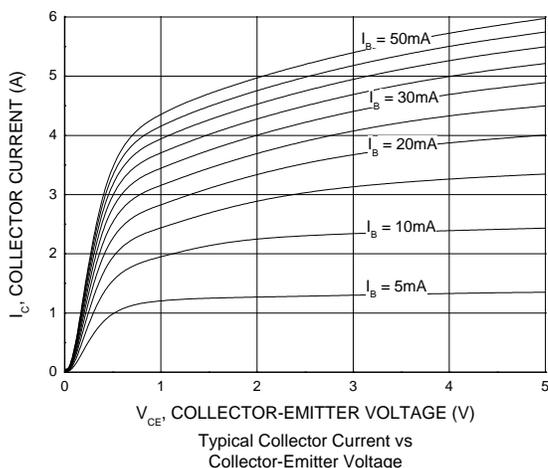
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>						
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	60	—	—	V	I <sub>C</sub> = 100μA
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	60	—	—	V	I <sub>C</sub> = 10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	7	—	—	V	I <sub>E</sub> = 100μA
Collector-Base Cutoff Current	I <sub>CBO</sub>	—	—	100	nA	V <sub>CB</sub> = 48V
		—	—	50	μA	V <sub>CB</sub> = 48V @T <sub>J</sub> = +150°C
Emitter Cutoff Current	I <sub>EBO</sub>	—	—	100	nA	V <sub>EB</sub> = 7V
Collector-Emitter Cutoff Current	I <sub>CES</sub>	—	—	100	nA	V <sub>CES</sub> = 48V
<b>ON CHARACTERISTICS (Note 9)</b>						
DC Current Gain	h <sub>FE</sub>	200	400	—	—	I <sub>C</sub> = 500mA, V <sub>CE</sub> = 2V
		200	330	—		I <sub>C</sub> = 1A, V <sub>CE</sub> = 2V
		100	180	—		I <sub>C</sub> = 2A, V <sub>CE</sub> = 2V
		50	100	—		I <sub>C</sub> = 3A, V <sub>CE</sub> = 2V
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	—	70	120	mV	I <sub>C</sub> = 1A, I <sub>B</sub> = 50mA
		—	180	270	mV	I <sub>C</sub> = 3A, I <sub>B</sub> = 300mA
Collector-Emitter Saturation Resistance	R <sub>CE(sat)</sub>	—	60	90	mΩ	I <sub>C</sub> = 3A, I <sub>B</sub> = 300mA
		—	0.86	1.0	V	I <sub>C</sub> = 1A, I <sub>B</sub> = 100mA
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	—	1.0	1.2		I <sub>C</sub> = 2A, I <sub>B</sub> = 200mA
		—	0.65	0.85	V	I <sub>C</sub> = 0.1A, V <sub>CE</sub> = 2V
Base-Emitter Turn-On Voltage	V <sub>BE(on)</sub>	—	0.65	0.85	V	I <sub>C</sub> = 0.1A, V <sub>CE</sub> = 2V
<b>SMALL SIGNAL CHARACTERISTICS</b>						
Current Gain-Bandwidth Product	f <sub>T</sub>	—	140	—	MHz	V <sub>CE</sub> = 10V, I <sub>C</sub> = 100mA, f = 10MHz
Output Capacitance	C <sub>obo</sub>	—	17	—	pF	V <sub>CB</sub> = 10V, f = 1MHz
Delay Time	t <sub>d</sub>	—	15	—	ns	V <sub>CC</sub> = 12.5V, I <sub>C</sub> = 1A I <sub>B1</sub> = -I <sub>B2</sub> = 0.05A
Rise Time	t <sub>r</sub>	—	120	—	ns	
Turn-On Time	t <sub>(on)</sub>	—	135	—	ns	
Storage Time	t <sub>s</sub>	—	800	—	ns	
Fall Time	t <sub>f</sub>	—	300	—	ns	
Turn-Off Time	t <sub>(off)</sub>	—	1100	—	ns	

Note: 9. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

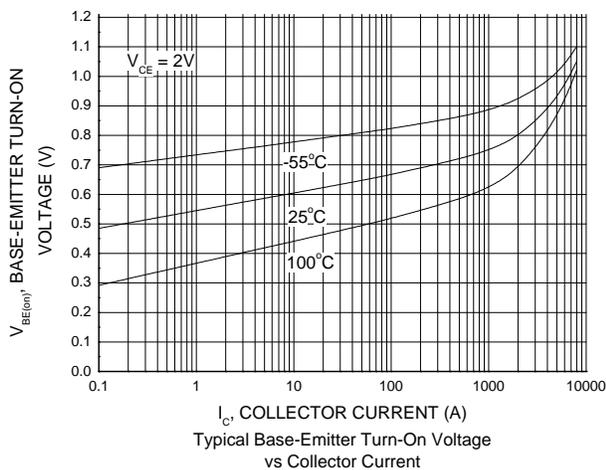
**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



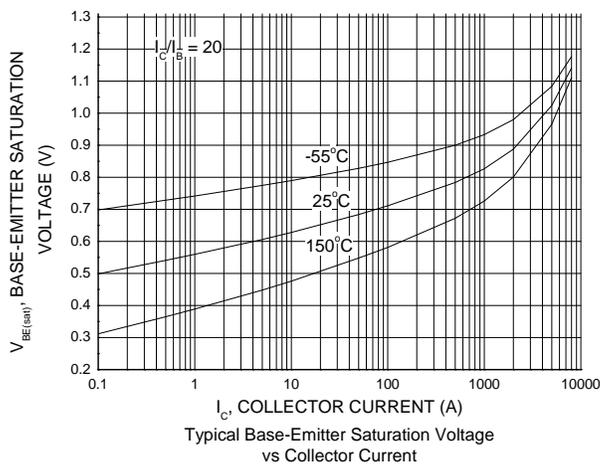
Typical DC Current Gain vs Collector Current



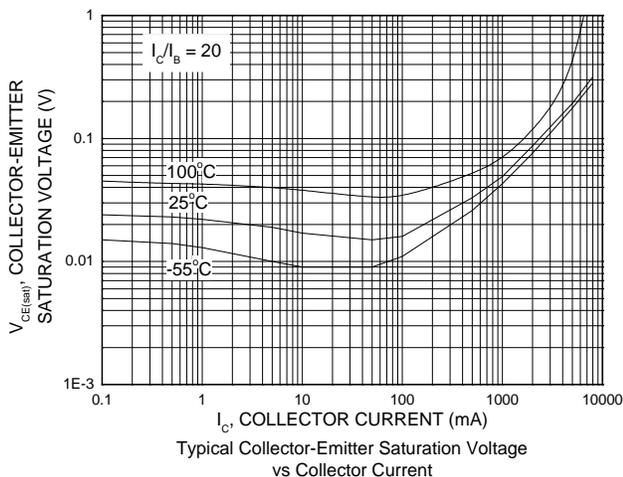
Typical Collector Current vs Collector-Emitter Voltage



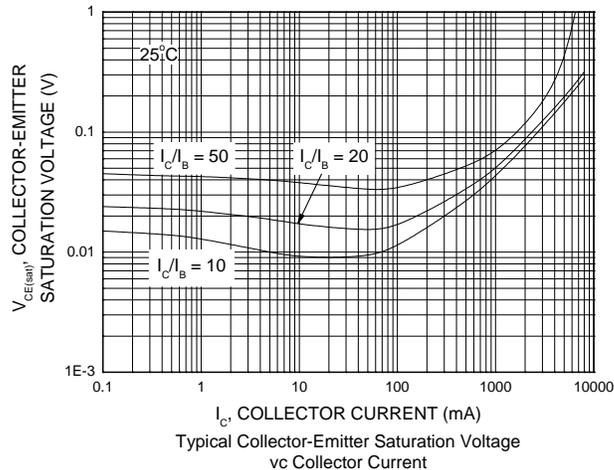
Typical Base-Emitter Turn-On Voltage vs Collector Current



Typical Base-Emitter Saturation Voltage vs Collector Current

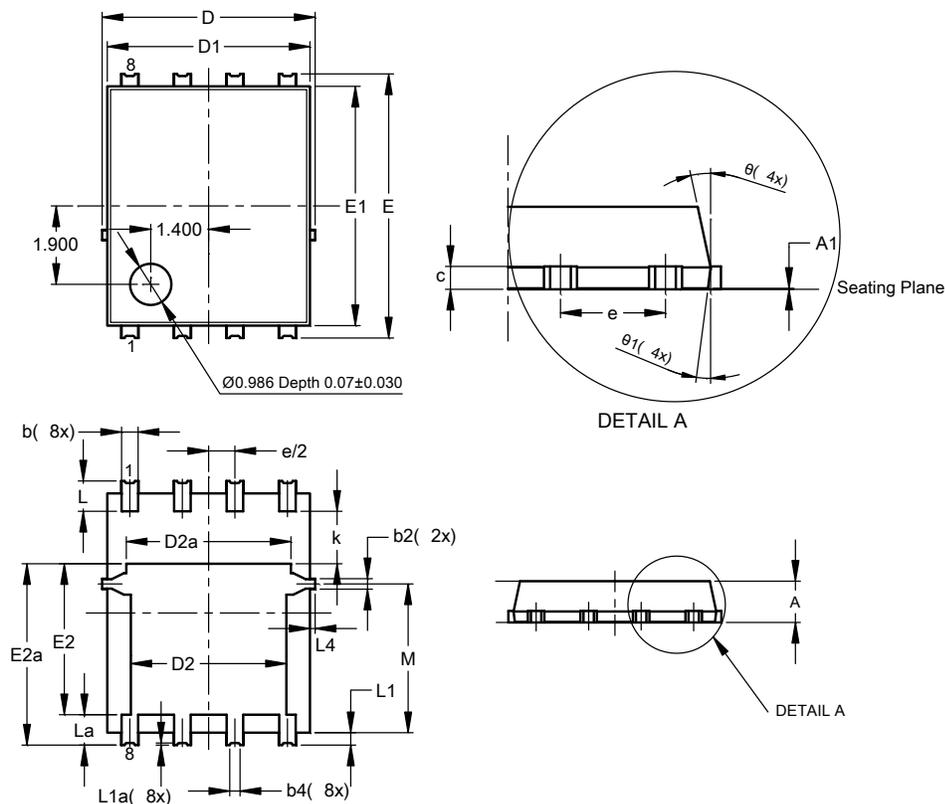


Typical Collector-Emitter Saturation Voltage vs Collector Current



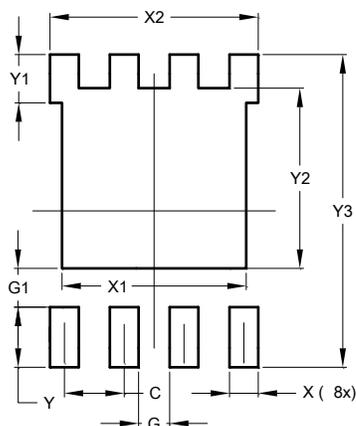
Typical Collector-Emitter Saturation Voltage vs Collector Current

## Package Outline Dimensions

**PowerDI5060-8 (SWP) (Type Q)**


PowerDI5060-8 (SWP) (Type Q)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0	0.05	--
b	0.30	0.50	0.41
b2	0.20	0.35	0.25
b4	0.25REF		
c	0.230	0.330	0.277
D	5.15 BSC		
D1	4.70	5.10	4.90
D2	3.56	3.96	3.76
D2a	3.78	4.18	3.98
E	6.40 BSC		
E1	5.60	6.00	5.80
E2	3.46	3.86	3.66
E2a	4.195	4.595	4.395
e	1.27BSC		
k	1.05	--	--
L	0.635	0.835	0.735
La	0.635	0.835	0.735
L1	0.200	0.400	0.300
L1a	0.050REF		
L4	0.025	0.225	0.125
M	3.205	4.005	3.605
θ	10°	12°	11°
θ1	6°	8°	7°
All Dimensions in mm			

## Suggested Pad Layout

**PowerDI5060-8 (SWP) (Type Q)**


Dimensions	Value (in mm)
C	1.270
G	0.660
G1	0.820
X	0.610
X1	4.100
X2	4.420
Y	1.270
Y1	1.020
Y2	3.810
Y3	6.610